

1-1734101-0 ✓ ACTIVE

CHAMP | CHAMP .050 Series I

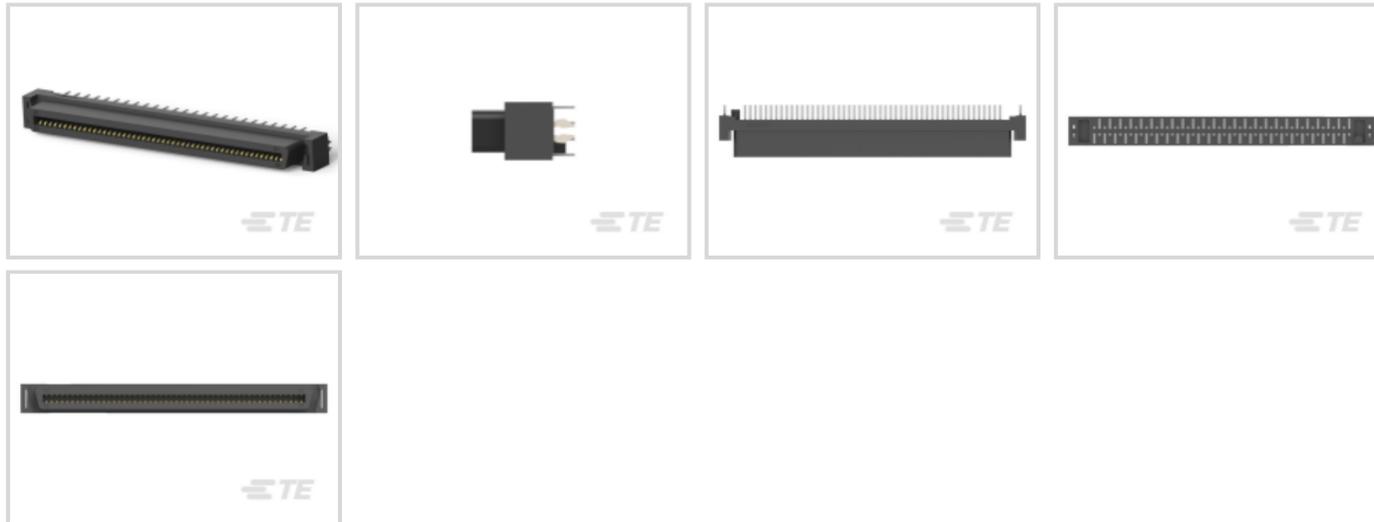
TE Internal #: 1-1734101-0

PCB Mount Receptacle, Vertical, Board-to-Board, 100 Position, 1.27 mm [.05 in] Centerline, Gold Flash, Through Hole - Solder, CHAMP .050 Series I

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **100**

Centerline (Pitch): **1.27 mm [.05 in]**

## Features

### Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Stackable	No
PCB Mount Orientation	Vertical
Number of Positions	100

### Electrical Characteristics

Dielectric Withstanding Voltage (Max)	750 VAC
Insulation Resistance	4 MΩ
Operating Voltage	250 VAC

### Body Features

PCB Retention Feature Material	Brass
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PCB Retention Feature Plating Material	Tin-Copper over Nickel
Connector Profile	Standard
Primary Product Color	Black

#### Contact Features

Contact Layout	Matrix
PCB Contact Termination Area Plating Material Thickness	3.8 $\mu\text{m}$ [149.606 $\mu\text{in}$ ]
Mating Tab Width	.75 mm[.03 in]
Mating Tab Thickness	.3 mm[.012 in]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Finish	Matte
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold Flash
	30 $\mu\text{in}$
Contact Type	Socket
Contact Current Rating (Max)	1 A

#### Termination Features

Rectangular Termination Post & Tail Thickness	.32 mm[.013 in]
Rectangular Termination Post & Tail Width	.5 mm[.02 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

#### Mechanical Attachment

PCB Mount Alignment Type	Locating Posts
PCB Mount Retention Type	Boardlock, Retention Leg
Mating Alignment	With
Mating Alignment Type	Polarized
PCB Mount Retention	With
PCB Mount Alignment	With
Connector Mounting Type	Board Mount

#### Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	Matte



### Dimensions

Connector Height	10 mm[.393 in]
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### Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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### Operation/Application

Assembly Process Feature	None
Circuit Application	Signal

### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	54
Packaging Type	Package

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

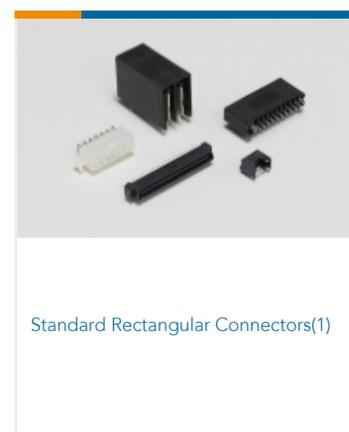
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Also in the Series | CHAMP .050 Series I



## Documents

### Product Drawings

[Champ050 series,100pos,Au over PdNi](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1734101-0\\_E.2d\\_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1734101-0\\_E.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1734101-0\\_E.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

[Application Specification](#)

English

[CHAMP .050 High Density Connector](#)



English

[Application Specification](#)

English

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[Product Environmental Compliance](#)

[TE Material Declaration](#)

English